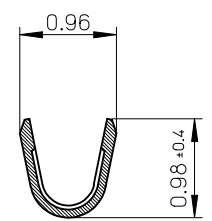
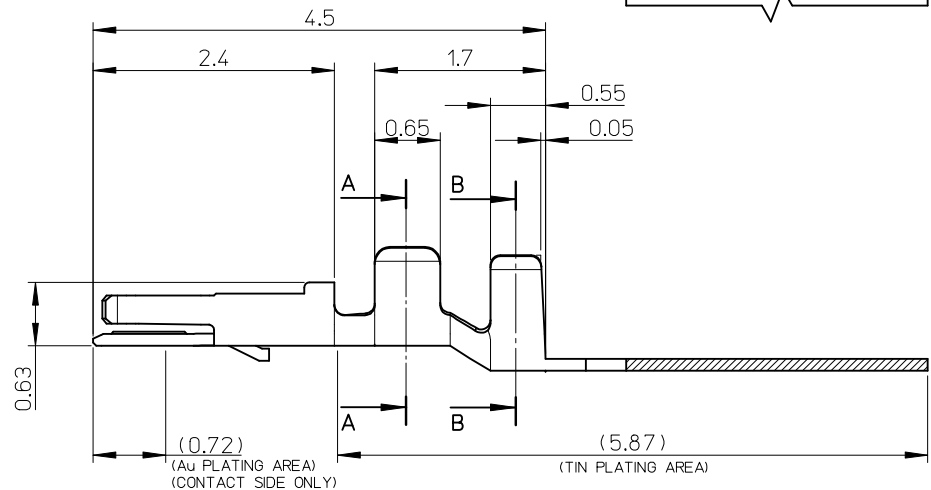
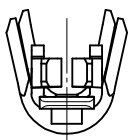
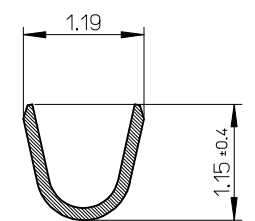


NOTES

- 適合ハウジング: 503764シリーズ
APPLICABLE HPUSING : 503764 SERIES
- 材質 : 銅合金
MATERIAL : COPPER ALLOY
- メッキ仕様
PLATING
接点部: 金メッキ
バレル部: 錫メッキ
ニッケル下地メッキ
CONTACT : GOLD PLATING
BARREL : TIN PLATING
NICKEL UNDER PLATING
- 圧着後CS-503765-001の内容を満たす事
FULFILL THE CONTENTS OF CS-503765-001 AFTER CRIMP.
- 圧着時の注意事項としてATS-57427-000を参照
AS ATTENTION AT THE TIME OF CRIMP, REFER TO ATS-57427-000



SECTION A-A



SECTION B-B

| | | | |
|----------------|-------------|------------|-------|
| ∅ 0.5 - 0.7 mm | AWG #28 -30 | 5037650098 | CHAIN |
| INS. RANGE | WIRE RANGE | ORDER No. | FORM |

| | | | | | | | |
|---|---------------------------------------|---|----------------------------|-------------------------------|---|------------------------|------------------------|
| RELEASED EC NO: J2014-1278 DRWN: YWAKE 2014/03/03 CHKD: KASAKAWA 2014/03/03 APPR: NUKITA 2014/03/05 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE 20:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| | 10 UNDER | ± 0.2 | DRAWN BY YWAKE | DATE 2014/03/03 | TITLE 1.0 WORE TO BOARD CONN. R/A H=1.5MM REC CRIMP TERM molex | | |
| | 10 OVER 30 UNDER | ± 0.25 | CHECKED BY KASAKAWA | DATE 2014/03/03 | | | |
| | 30 OVER | ± 0.3 | APPROVED BY NUKITA | DATE 2014/03/05 | | | |
| ANGULAR ± 3 ° | | MATERIAL NO. SEE CHART | | DOCUMENT NO. SD-503765-001 | | SHEET NO. 1 OF 1 | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | |